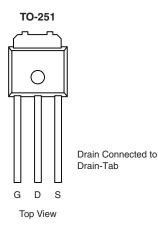


RoHS

COMPLIANT

N-Channel 200V (D-S) MOSFET

PRODUCT SUMMARY				
V _{DS} (V)	R_{DS(on)} (Ω)	I _D (A)		
200	0.056 at V _{GS} = 10 V	25		
200	0.070 at V _{GS} = 6 V	23		

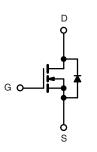


FEATURES

- TrenchFET[®] Power MOSFET
- 175 °C Junction Temperature
- PWM Optimized
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

• Primary Side Switch



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage		V _{DS}	200	v		
Gate-Source Voltage	V _{GS}	± 20	v			
Continuous Drain Current (T _{.1} = 175 °C) ^b	T _C = 25 °C	1-	25			
Continuous Drain Current $(1_J = 175 \text{ °C})^2$	T _C = 125 °C	I _D	17			
Pulsed Drain Current	I _{DM}	60	А			
Continuous Source Current (Diode Conduction)	۱ _S	19				
Avalanche Current	I _{AS}	25				
Single Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	18	mJ		
Maximum Power Dissipation	T _C = 25 °C	P _D	145 ^b	w		
	T _A = 25 °C		3.5 ^a	vv		
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 175	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
hunding to Ampliant	t ≤ 10 s	R _{thJA}	15	18	°C/W		
Junction-to-Ambient ^a	Steady State		40	50			
Junction-to-Case (Drain)		R _{thJC}	0.85	1.1			

Notes:

a. Surface mounted on 1" x 1" FR4 board.

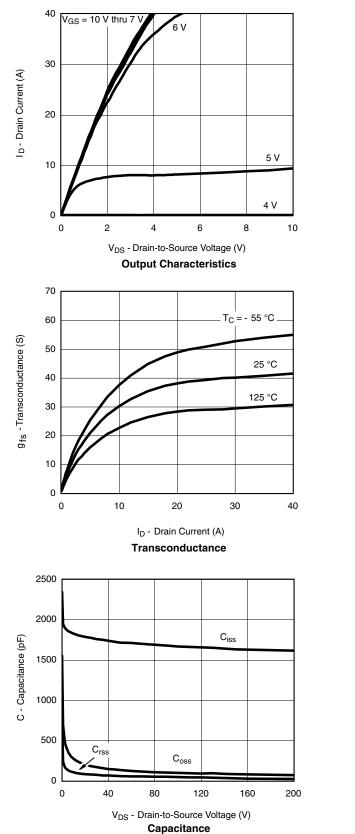
b. See SOA curve for voltage derating.



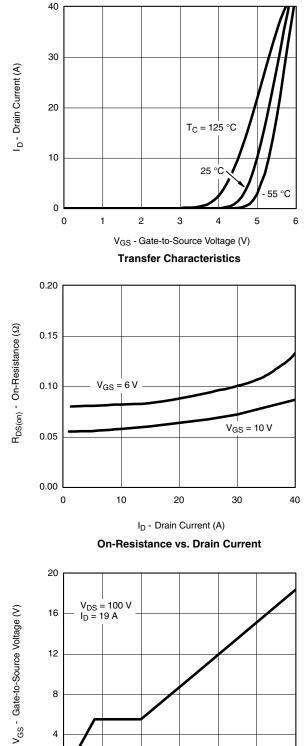
Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 250 \mu\text{A}$	200			v	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \ \mu A$	2		4	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	/ _{GS} = 0 V		1		
Zero Gate Voltage Drain Current	I _{DSS}	V_{DS} = 200 V, V_{GS} = 0 V, T_{J} = 125 °C			50	μΑ	
		$V_{DS} = 200 \text{ V}, \text{ V}_{GS} = 0 \text{ V}, \text{ T}_{J} = 175 ^{\circ}\text{C}$			250		
On-State Drain Current ^b	I _{D(on)}	$V_{DS} = 5 V, V_{GS} = 10 V$	40			Α	
		$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}$		0.056			
	Р	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}, \text{ T}_{J} = 125 ^{\circ}\text{C}$		0.130		Ω	
Drain-Source On-State Resistance ^D	R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5 \text{ A}, \text{ T}_{J} = 175 ^{\circ}\text{C}$		0.260			
		$V_{GS} = 6 V, I_D = 5 A$		0.070		1	
Forward Transconductance ^b	9 _{fs}	V _{DS} = 15 V, I _D = 19 A		35		S	
Dynamic ^a				•			
Input Capacitance	C _{iss}			2400			
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 25 V, F = 1 MHz		280		pF	
Reverse Transfer Capacitance	C _{rss}			180			
Total Gate Charge ^c	Qg			40			
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 100 V, V_{GS} = 10 V, I_{D} = 19 A		10		nC	
Gate-Drain Charge ^c	Q _{gd}			15			
Gate Resistance	R _g		0.5		2.9	Ω	
Turn-On Delay Time ^c	t _{d(on)}			15	25		
Rise Time ^c	t _r	V_{DD} = 100 V, R_L = 5.2 Ω		50	75	ns	
Turn-Off Delay Time ^c	t _{d(off)}	$\text{I}_\text{D}\cong$ 19 A, V_GEN = 10 V, R_g = 2.5 Ω		30	45		
Fall Time ^c	t _f			60	90		
Source-Drain Diode Ratings and Chara	acteristics (1	C = 25 °C)			1		
Pulsed Current	I _{SM}				50	А	
Diode Forward Voltage ^b	V _{SD}	$I_{F} = 19 \text{ A}, \text{ V}_{GS} = 0 \text{ V}$		0.9	1.5	V	
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 19 A, dl/dt = 100 A/μs		180	250	ns	

Notes: a. Guaranteed by design, not subject to production testing. b. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 %. c. Independent of operating temperature.





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Qg - Total Gate Charge (nC)

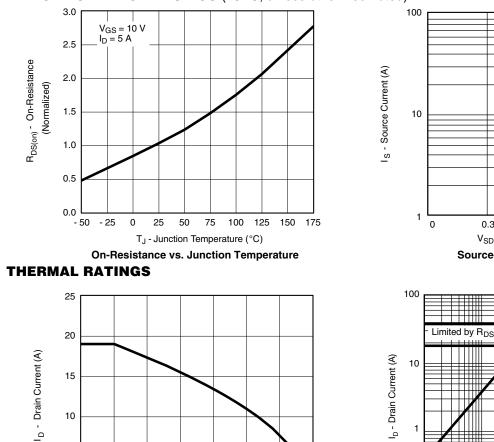
Gate Charge

T_C - Case Temperature (°C)

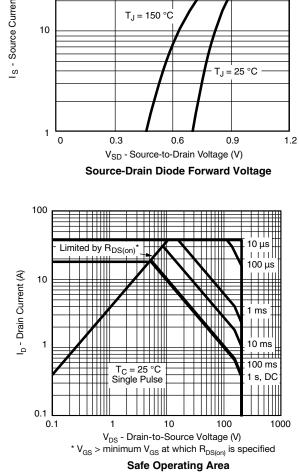
Maximum Avalanche Drain Current

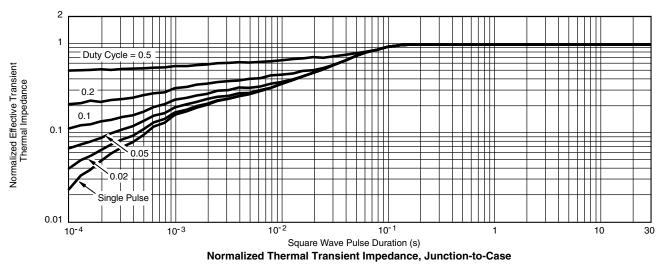
vs. Case Temperature





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

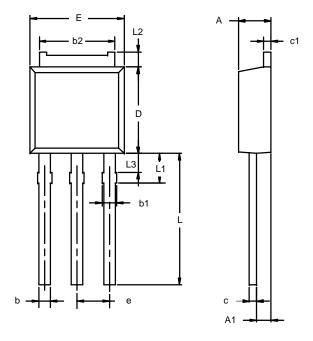




VBFB1208N



TO-251AA



	MILLIM	MILLIMETERS		
Dim	Min	Max	Min	Max
Α	2.21	2.38	0.087	0.094
A1	0.89	1.14	0.035	0.045
b	0.71	0.89	0.028	0.035
b1	0.76	1.14	0.030	0.045
b2	5.23	5.43	0.206	0.214
С	0.46	0.58	0.018	0.023
c1	0.46	0.58	0.018	0.023
D	5.97	6.22	0.235	0.245
E	6.48	6.73	0.255	0.265
е	2.28	BSC	0.090	BSC
L	3.89	9.53	0.153	0.375
L1	1.91	2.28	0.075	0.090
L2	0.89	1.27	0.035	0.050
L3	1.15	1.52	0.045	0.060

Note: Dimension L3 is for reference only.



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